



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-12-07
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SPC572L64E3BC6AR	B9YE*FE64ABQ	A	1054	2016-12-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	520.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiPdAu	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14-14-1	100	gull wing	
Comment	TQFP 100 14x14x1.0 1.0 ExpadDown			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	B9YE*FE64ABQ									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or Dies (choose)	Other inorganic materials	17.734	mg	supplier	die	Silicon (Si)	7440-21-3		17.179	mg	968706	33038				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.039	mg	2199	72				
				supplier	metallization	Copper (Cu)	7440-50-8		0.233	mg	13138	448				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.038	mg	2143	73				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.010	mg	564	19				
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	113	4				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.053	mg	2988	102				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.180	mg	10149	346				
				Leadframe	Copper & its alloys	220.335	mg	supplier	alloy	Copper (Cu)	7440-50-8		210.198	mg	953993	404227
								supplier	alloy	Nickel (Ni)	7440-02-0		6.555	mg	29750	12606
supplier	alloy	Magnesium (Mg)	7439-95-4						0.328	mg	1489	631				
supplier	alloy	Silicon (Si)	7440-21-3						1.420	mg	6445	2731				
supplier	metallization	Nickel (Ni)	7440-02-0						1.681	mg	7629	3233				
supplier	metallization	Palladium (Pd)	7440-05-3						0.108	mg	490	208				
supplier	metallization	Gold (Au)	7440-57-5						0.045	mg	204	87				
supplier	glue	Silver (Ag)	7440-22-4						3.994	mg	894914	7681				
Die attach	Other Organic Materials	4.463	mg	supplier	glue	Isobornyl Methacrylate	7534-94-3		0.335	mg	75062	644				
				supplier	glue	Bismaleimide resin	35325-39-4		0.134	mg	30024	258				
				supplier	wire	Copper (Cu)	7440-50-8		0.833	mg	1000000	1602				
Bonding wires	Other inorganic materials	0.833	mg	supplier	wire	Copper (Cu)	7440-50-8		0.833	mg	1000000	1602				
Encapsulation	Other Organic Materials	276.635	mg	supplier	mold compound	Silica, vitreous	60676-86-0		239.012	mg	863998	459638				
				supplier	mold compound	Epoxy Resin	25068-38-6		20.748	mg	75001	39900				
				supplier	mold compound	Phenol Resin	29690-82-2		13.832	mg	50001	26600				
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		1.383	mg	5000	2660				
				supplier	mold compound	Quartz	14808-60-7		0.830	mg	3000	1596				
				supplier	mold compound	Carbon black	1333-86-4		0.830	mg	3000	1596				